

RELIABILITY MONITOR

PROCESS: 0.6 μ m Double Poly, Single Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2502	C3	MAR '00	25253	0005	Carsem S	DM941226AA	SOIC	48	232	0
DS2502	C3	JUN '00	25568	0011	Carsem S	DM941230AG	SOIC	48	231	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2502	C3	MAR '00	25254	0005	Carsem S	DM941226AA	SOIC	336	77	0
DS2502	C3	JUN '00	25569	0011	Carsem S	DM941230AG	SOIC	336	77	0
DS2502	C3	MAR '00	25254	0005	Carsem S	DM941226AA	SOIC	1000	77	0

TOTALS FOR: 0.6 μ m Double Poly, Single Metal (Ti/Ti) FAIL RATE (Fits): 57 DEVICE HRS: 1.61E+07 0

RELIABILITY MONITOR

PROCESS: 0.6 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	DATE	MONITOR	JOB NO	DATE	ASSEMBLY	CODE	FACILITY	LOT NO.	PACKAGE	READ	POINT	QTY	FAILS
DS21Q43	A3-A	JUN '00		25504	0014	ATK (Anam, K)			DN004571AAB	LQFP	48	224	0	

TOTALS FOR: 0.6 μ m Single Poly, Single Metal FAIL RATE (Fits): 666 DEVICE HRS: 1.38E+06 0

RELIABILITY MONITOR

PROCESS: 0.6 µm Single Poly, Single Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2118M	B1	MAR '00	25233	0005	ATK (Anam, K)	ZN946350AAG	SSOP	48	234	0
DS2118M	B1	JUN '00	25555	0020	ATK (Anam, K)	DN009554AAD	SSOP	48	234	0
DS2401	C2	SEP '00	25965	0034	Fastech	DA005635AKA	TO92	48	234	0
DS2401	C2	JUN '00	25560	0022	Fastech	DA952309AKA	TO92	48	234	0
DS5002	C4	APR '00	25430	0004	Carsem	DM925587AAF	MQFP	48	199	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2118M	B1	MAR '00	25234	0005	ATK (Anam, K)	ZN946350AAG	SSOP	336	75	0
DS2118M	B1	JUN '00	25556	0020	ATK (Anam, K)	DN009554AAD	SSOP	336	77	0
DS2118M	B1	MAR '00	25234	0005	ATK (Anam, K)	ZN946350AAG	SSOP	1000	74	0
DS2118M	B1	JUN '00	25556	0020	ATK (Anam, K)	DN009554AAD	SSOP	1000	77	0
DS2401	C2	JUN '00	25561	0022	Fastech	DA952309AKA	TO92	336	77	0
DS2401	C2	JUN '00	25561	0022	Fastech	DA952309AKA	TO92	1000	77	0

TOTALS FOR: 0.6 µm Single Poly, Single Metal (Ti/Ti) FAIL RATE (Fits): 25 DEVICE HRS: 3.62E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Double Poly, Double Metal (Ti/TiN layers used on all Metals)

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	JUN '00	25620	0022	ATK (Anam, K)	DN012234ABA	LQFP	48	233	0
DS2154	A2	MAR '00	25241	0007	ATP (Anam, PI)	DK948587AAA	LQFP	48	234	1

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2154	A2	JUN '00	25621	0022	ATK (Anam, K)	DN012234ABA	LQFP	336	75	0
DS2154	A2	JUN '00	25621	0022	ATK (Anam, K)	DN012234ABA	LQFP	1000	74	0
DS2154	A2	MAR '00	25242	0007	ATP (Anam, PI)	DK948587AAA	LQFP	336	90	0
DS2154	A2	MAR '00	25242	0007	ATP (Anam, PI)	DK948587AAA	LQFP	1000	90	0

TOTALS FOR: 0.8 μ m Double Poly, Double Metal (Ti/T FAIL RATE (Fits): 31 DEVICE HRS: 6.51E+07 1

RELIABILITY MONITOR

PROCESS: 0.8 μ m Double Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS87C520	A14	NOV '99	24800	9931	ATK (Anam, K)	DN901118AAB	PLCC	48	219	0
DS87C520	A14	FEB '00	25120	0004	ATP (Anam, PI)	DK935356AAB	PLCC	48	228	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS87C520	A14	NOV '99	24801	9931	ATK (Anam, K)	DN901118AAB	PLCC	336	77	0
DS87C520	A14	NOV '99	24801	9931	ATK (Anam, K)	DN901118AAB	PLCC	1000	77	0
DS87C520	A14	FEB '00	25121	0004	ATP (Anam, PI)	DK935356AAB	PLCC	336	77	0

TOTALS FOR: 0.8 μ m Double Poly, Single Metal FAIL RATE (Fits): 21 DEVICE HRS: 4.32E+07 0

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Double Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1302	A3	JUN '99	23938	9905	ATP (Anam, PI)	DK824165AAA	PDIP	48	234	0
DS1302	A3	MAR '00	25211	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	48	234	1
DS1302	A3	AUG '00	25931	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	48	234	0
DS1302	A3	JUN '00	25535	0018	CPS (ChipPac, China)	DH008331AAA	PDIP	48	234	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1302	A3	JUN '99	24513	9905	ATP (Anam, PI)	DK824165AAA	PDIP	336	77	0
DS1302	A3	JUN '99	24513	9905	ATP (Anam, PI)	DK824165AAA	PDIP	1000	75	0
DS1302	A3	JUN '00	25536	0018	CPS (ChipPac, China)	DH008331AAA	PDIP	336	77	0
DS1302	A3	MAR '00	25212	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	336	77	0
DS1302	A3	MAR '00	25212	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	1000	76	0

TOTALS FOR: 0.8 μ m Single Poly, Double Metal FAIL RATE (Fits): 71 DEVICE HRS: 2.85E+07 1

RELIABILITY MONITOR

PROCESS: 0.8 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1232	C2-L	APR '00	25421	0011	OSEP	DE952427AAD	SOIC	48	233	0
DS1232	C2-L	JUL '00	25787	0024	OSEP	DE014522ADB	SOIC	48	234	1
DS1621	A7	MAR '00	25220	9950	OSEP	DE940040AAC	SOIC	48	237	0
DS2109	A7	DEC '99	24808	9842	Carsem	DM812689AA	SOIC	48	232	2
DS21S07	C1-	FEB '00	25098	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	48	234	0
DS21S07	C1-	MAY '00	25446	0013	Carsem S	DM002285AAF	TSSOP	48	234	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2109	A7	DEC '99	24809	9842	Carsem	DM812689AA	SOIC	336	77	0
DS2109	A7	DEC '99	24809	9842	Carsem	DM812689AA	SOIC	1000	77	0
DS21S07	C1-	FEB '00	25099	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	336	77	0
DS21S07	C1-	FEB '00	25099	9937	ATP (Anam, PI)	DK926747AAP	TSSOP	1000	76	0
DS21S07	C1-	MAY '00	25447	0013	Carsem S	DM002285AAF	TSSOP	336	77	0

TOTALS FOR: 0.8 μ m Single Poly, Single Metal FAIL RATE (Fits): 49 DEVICE HRS: 8.59E+07 3

RELIABILITY MONITOR

PROCESS: 1.2 µm Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1000	E3	OCT '99	24791	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	48	234	1
DS1000	E3	APR '00	25406	0009	CPS (ChipPac, China)	DH949661AEA	PDIP	48	234	0
DS1233	A5	JAN '00	25036	9952	Carsem	DM929359AB	SOT223	48	229	0
DS1267	A1	AUG '99	24343	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	48	228	0
DS1267	A2	FEB '00	25175	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	48	226	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS1000	E3	OCT '99	24792	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	336	77	0
DS1000	E3	APR '00	25407	0009	CPS (ChipPac, China)	DH949661AEA	PDIP	336	77	0
DS1000	E3	OCT '99	24792	9944	CPS (ChipPac, China)	DH927108AJC	PDIP	1000	75	0
DS1000	E3	APR '00	25407	0009	CPS (ChipPac, China)	DH949661AEA	PDIP	1000	77	0
DS1233	A5	JAN '00	25037	9952	Carsem	DM929359AB	SOT223	336	77	0
DS1233	A5	JAN '00	25037	9952	Carsem	DM929359AB	SOT223	1000	77	0
DS1267	A1	AUG '99	24344	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	336	77	0
DS1267	A1	AUG '99	24344	9823	ATP (Anam, PI)	DK807766AAE	TSSOP	1000	75	0

TOTALS FOR: 1.2 µm Single Poly, Single Metal FAIL RATE (Fits): 19 DEVICE HRS: 1.04E+08 1

RELIABILITY MONITOR

PROCESS: 5.0 μ m Single Poly, Single Metal

STRESS: INFANT LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2108	B7	MAY '00	25525	0019	ATP (Anam, PI)	DK007198AAF	SOIC	48	231	0
DS2108	B7	FEB '00	25106	9951	ATP (Anam, PI)	DK940069AAC	SOIC	48	234	0
DS2108	B7	AUG '00	25857	0029	ATP (Anam, PI)	DK016058AA	SOIC	48	231	0

STRESS: HIGH VOLTAGE LIFE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE CODE	ASSEMBLY FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAILS
DS2108	B7	FEB '00	25107	9951	ATP (Anam, PI)	DK940069AAC	SOIC	336	77	0
DS2108	B7	MAY '00	25526	0019	ATP (Anam, PI)	DK007198AAF	SOIC	336	77	0
DS2108	B7	FEB '00	25107	9951	ATP (Anam, PI)	DK940069AAC	SOIC	1000	76	0
DS2108	B7	MAY '00	25526	0019	ATP (Anam, PI)	DK007198AAF	SOIC	1000	77	0

TOTALS FOR: 5.0 μ m Single Poly, Single Metal FAIL RATE (Fits): 38 DEVICE HRS: 2.38E+07 0